

规格书编号：

SPEC NO: HDF1250A8S6SP00

产品规格书

SPECIFICATION

CUSTOMER 客户: _____
PRODUCT 产品: _____ SAW FILTER _____
MODEL NO 型号: _____ HDF1250A8-S6 _____
MARKING 印字: _____ HDF6G358 _____
PREPARED 编制: _____ CHECKED 审核: _____
APPROVED 批准: _____ D A T E 日期: _____ 2014-3-25 _____

客户确认 CUSTOMER RECEIVED:		
审核 CHECKED	批准 APPROVED	日期 DATE

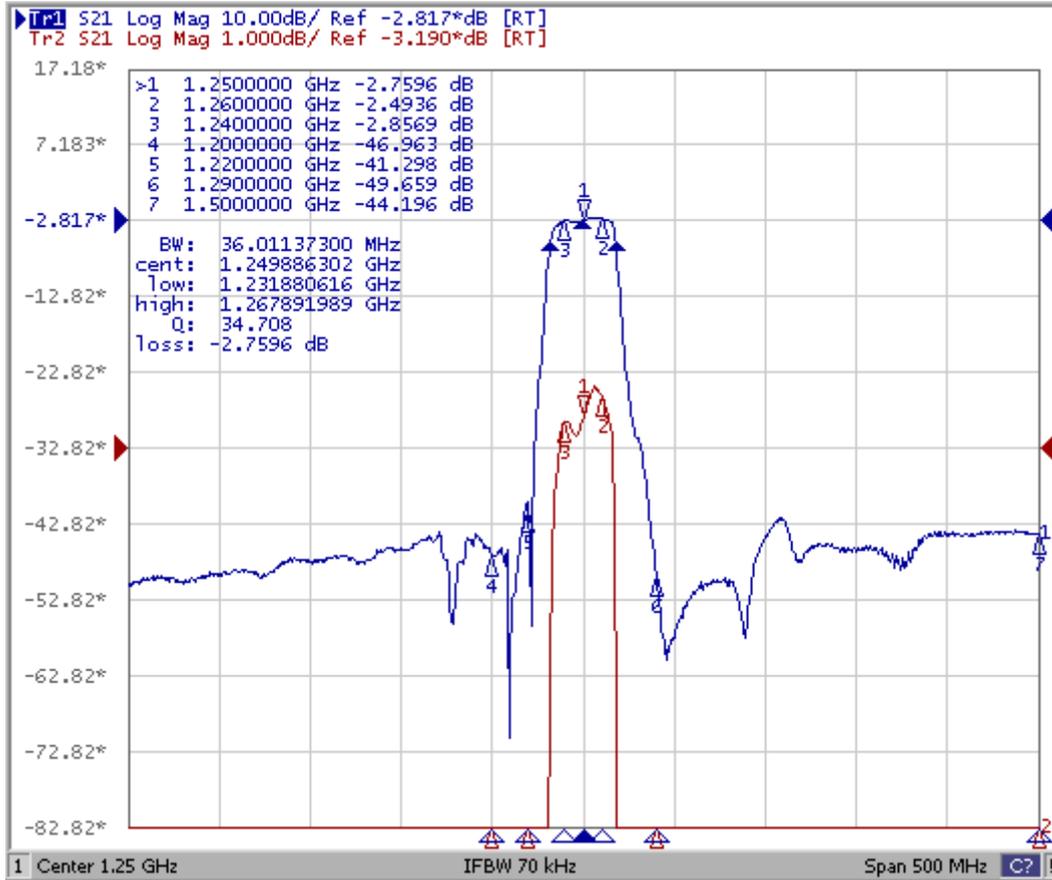
无锡市好达电子有限公司
Shoulder Electronics Limited

1. ELECTRICAL SPECIFICATION

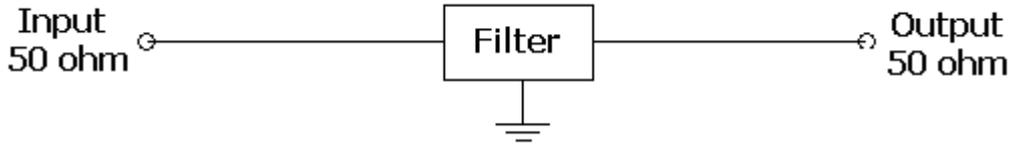
Maximum Input Power	+10dBm
DC voltage	10V
Storage Temperature Range	-45°C to +85°C
Operation Temperature Range	-40°C to +85°C

Electronic Characteristics

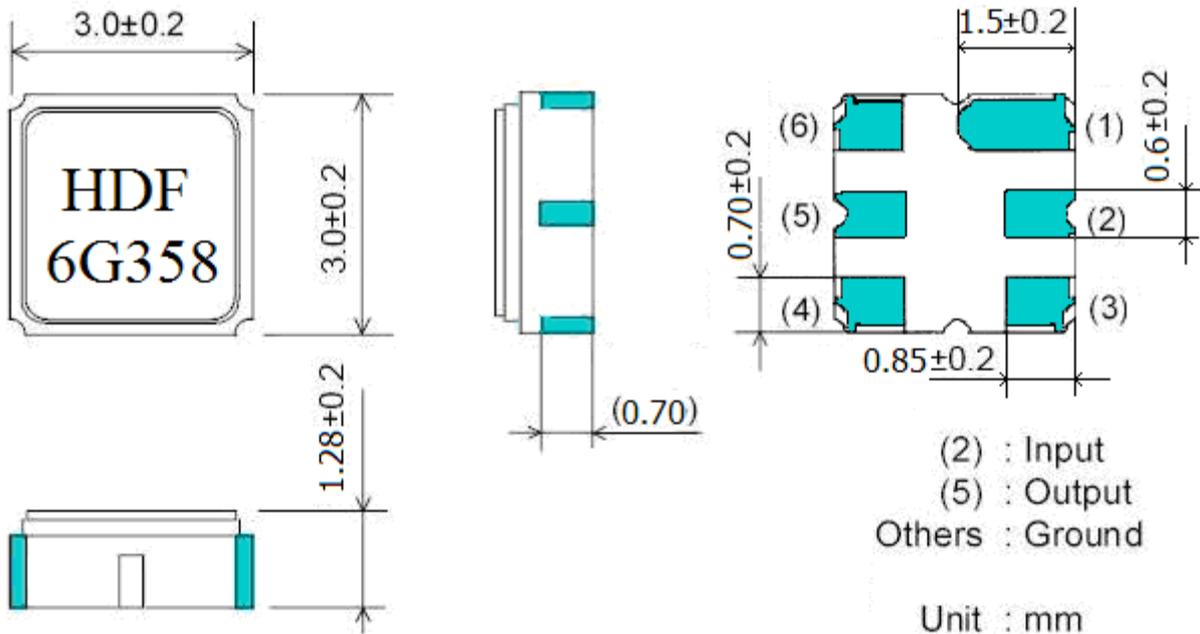
	Unit	Minimum	Typical	Maximum
Center Frequency	MHz	-	1250	-
Insertion Loss (1250 MHz)	dB		2.0	3.5
Amplitude Ripple(1250 ± 10 MHz)	dB		0.9	2.0
Absolute Attenuation				
10 ~ 1200 MHz	dB	40	50	-
1200 ~ 1220 MHz		30	35	
1290 ~ 1500 MHz		40	45	
Input/Output Impedance	Ohms		50	



2. TEST CIRCUIT



3. DIMENSION



4. ENVIRONMENTAL CHARACTERISTICS

4.1 High temperature exposure

Subject the device to +85°C for 16 hours. Then release the filter into the room conditions for 24 hours prior to the measurement. It shall fulfill the specifications in 2-2.

4.2 Low temperature exposure

Subject the device to -40°C for 16 hours. Then release the device into the room conditions for 24 hours prior to the measurement. It shall fulfill the specifications in 2-2.

4.3 Temperature cycling

Subject the device to a low temperature of -40°C for 30 minutes. Following by a high temperature of +85°C for 30 Minutes. Then release the device into the room conditions for 24 hours prior to the measurement. It shall meet the specifications in 2-2.

4.4 Resistance to solder heat

Dip the device terminals no closer than 1.5mm into the solder bath at 260°C ±10°C for 10±1 sec. Then release the device into the room conditions for 4 hours. The device shall meet the specifications in 2-2.

4.5 Solderability

Subject the device terminals into the solder bath at 245°C ±5°C for 5s, More than 95%

area of the terminals must be covered with new solder. It shall meet the specifications in 2-2.

4.6 Mechanical shock

Drop the device randomly onto the concrete floor from the height of 1m 3 times. the device shall fulfill the specifications in 2-2.

4.7 Vibration

Subject the device to the vibration for 1 hour each in x,y and z axes with the amplitude of 1.5 mm at 10 to 55 Hz. The device shall fulfill the specifications in 2-2.

5. REMARK

5.1 Static voltage

Static voltage between signal load & ground may cause deterioration & destruction of the component. Please avoid static voltage.

5.2 Ultrasonic cleaning

Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning

5.3 Soldering

Only leads of component may be soldered. Please avoid soldering another part of component.